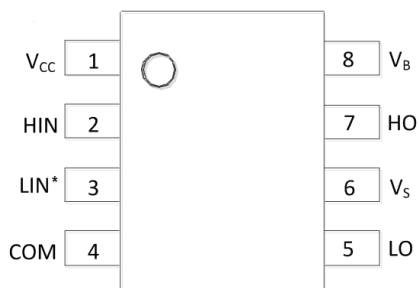


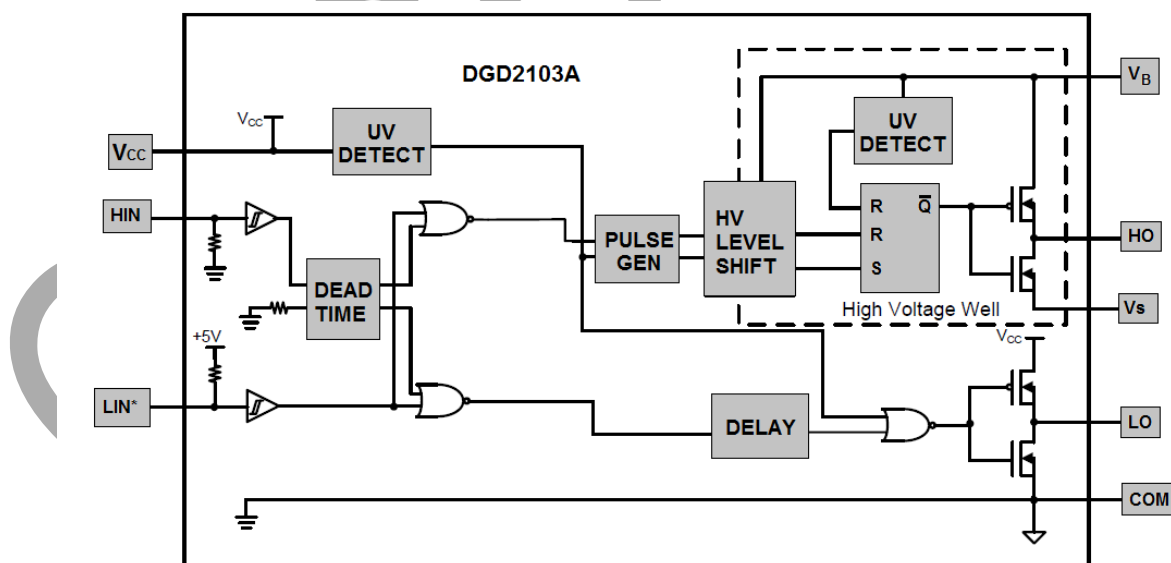
Pin Diagrams



Pin Descriptions

Pin Number	Pin Name	Function
1	V _{CC}	Logic and Low Side Supply
2	HIN	Logic Input for High-Side Gate Driver Output in Phase with HO
3	LIN*	Logic input for Low-Side Gate Driver Output out of Phase with LO
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	V _S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V _B	High-Side Floating Supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V _B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V _S	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN*)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P _D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	200	°C/W
Operating Temperature	T _J	+150	°C
Lead Temperature (Soldering, 10s)	T _L	+300	
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	V _B	V _S + 10	V _S + 20	V
High-Side Floating Supply Offset Voltage	V _S	(Note 6)	600	V
High-Side Floating Output Voltage	V _{HO}	V _S	V _B	V
Low-Side and Logic Fixed Supply Voltage	V _{CC}	10	20	V
Low-Side Output Voltage	V _{LO}	0	V _{CC}	V
Logic Input Voltage	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

 Note: 6. Logic operation for V_S of -5V to +600V.

DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, @ T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Logic "1" (HIN) & Logic "0" (LIN*) Input Voltage	V_{IH}	2.5	—	—	V	V_{CC} = 10V to 20V
Logic "0" (HIN) & Logic "1" (LIN*) Input Voltage	V_{IL}	—	—	0.8	V	V_{CC} = 10V to 20V
High-Level Output Voltage, $V_{BIAS} - V_O$	V_{OH}	—	0.05	0.2	V	I_O = 2mA
Low-Level Output Voltage, V_O	V_{OL}	—	0.02	0.1	V	I_O = 2mA
Offset Supply Leakage Current	I_{LK}	—	—	50	μA	$V_B = V_S = 600V$
Quiescent V_{BS} Supply Current	I_{BSQ}	—	30	55	μA	$V_{IN} = 0V$ or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	—	370	500	μA	$V_{IN} = 0V$ or 5V
Logic "1" Input Bias Current	I_{IN+}	—	3.0	10	μA	HIN = 5V, LIN* = 0V
Logic "0" Input Bias Current	I_{IN-}	—	—	5.0	μA	HIN = 0V, LIN* = 5V
V_{CC} Supply Under-Voltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	—
V_{CC} Supply Under-Voltage Negative Going Threshold	V_{CCUV-}	7.4	8.2	9.0	V	—
Output High Short Circuit Pulsed Current	I_{O+}	130	210	—	mA	$V_O = 0V$, $PW \leq 10\mu s$
Output Low Short Circuit Pulsed Current	I_{O-}	270	360	—	mA	$V_O = 15V$, $PW \leq 10\mu s$

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins: HIN and LIN*. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, C_L = 1000pF, @ T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Turn-On Propagation Delay	t_{ON}	—	680	820	ns	$V_S = 0V$
Turn-Off Propagation Delay	t_{OFF}	—	150	220	ns	$V_S = 600V$
Delay Matching, HO & LO Turn-On / Turn-Off	t_{DM}	—	—	60	ns	—
Turn-On Rise Time	t_R	—	100	170	ns	$V_S = 0V$
Turn-Off Fall Time	t_F	—	50	60	ns	$V_S = 0V$
Deadtime: $t_{DT\ LO-HO}$ & $t_{DT\ HO-LO}$	t_{DT}	400	520	650	ns	—

Timing Waveforms

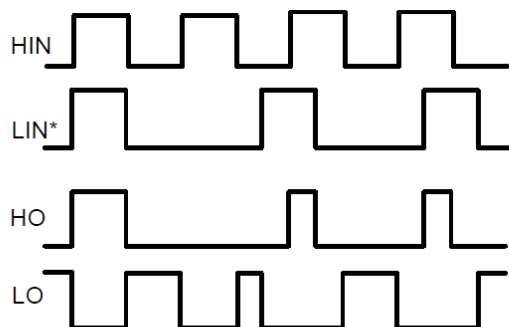


Figure 1. Input / Output Timing Diagram

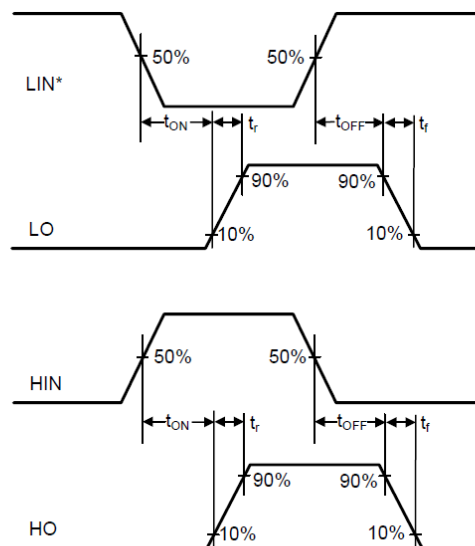


Figure 2. Switching Time Waveform Definitions

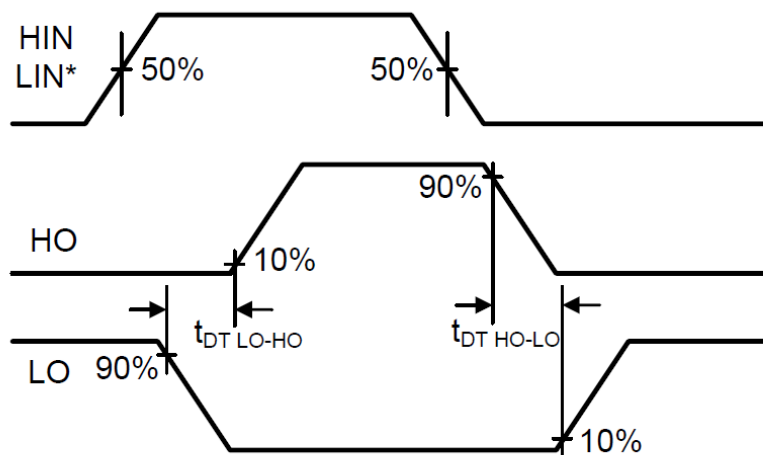


Figure 3. Deadtime Waveform Definitions

Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

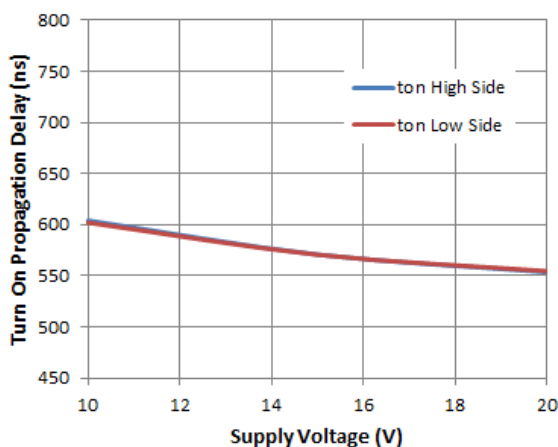


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

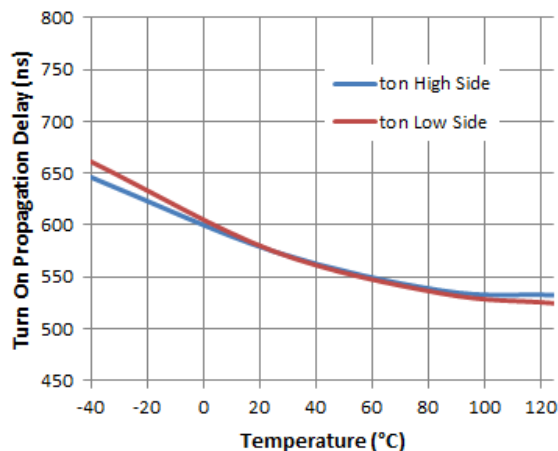


Figure 5. Turn-on Propagation Delay vs. Temperature

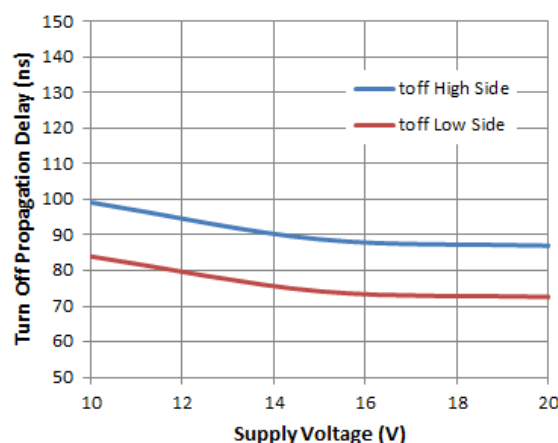


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

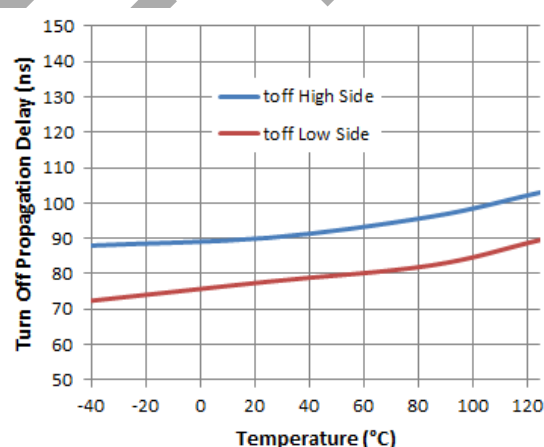


Figure 7. Turn-off Propagation Delay vs. Temperature

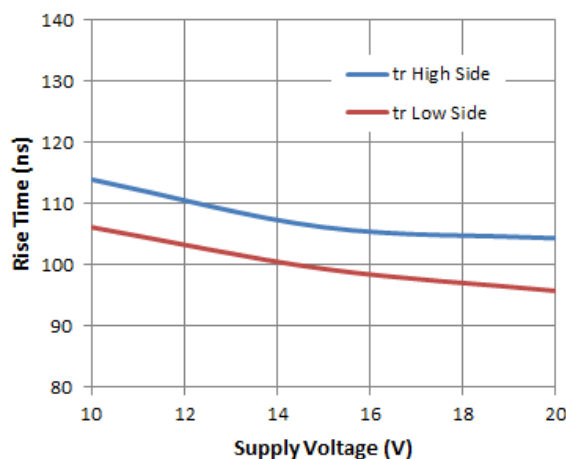


Figure 8. Rise Time vs. Supply Voltage

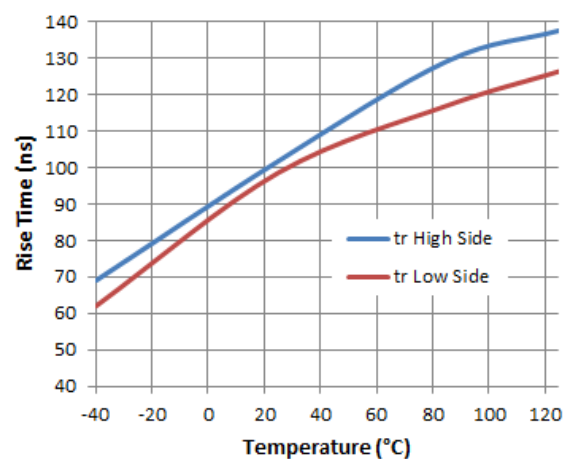


Figure 9. Rise Time vs. Temperature

Typical Performance Characteristics (Cont.)

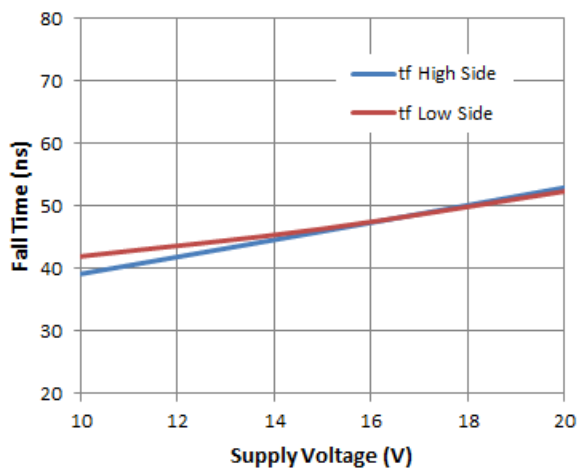


Figure 10. Fall Time vs. Supply Voltage

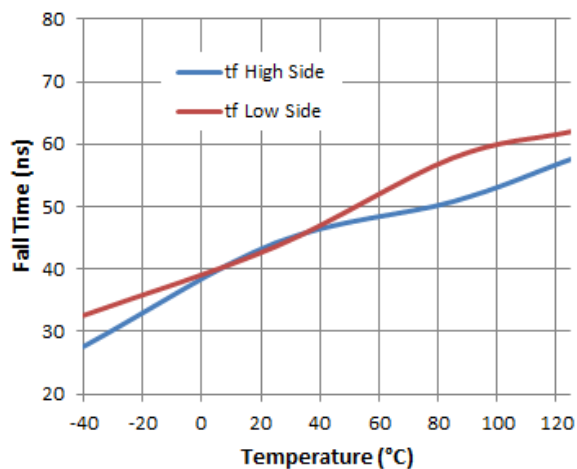


Figure 11. Fall Time vs. Temperature

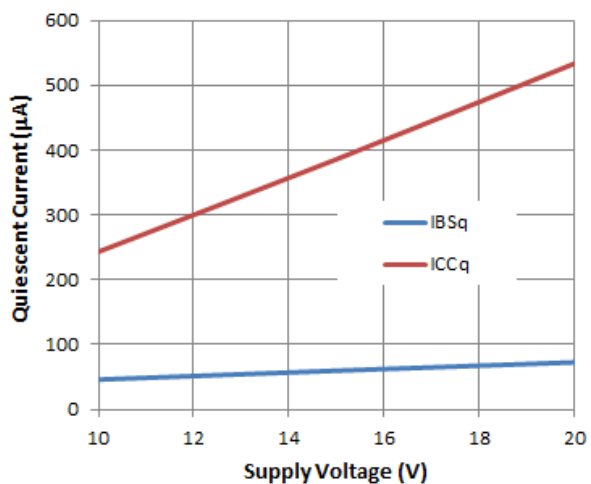


Figure 12. Quiescent Current vs. Supply Voltage

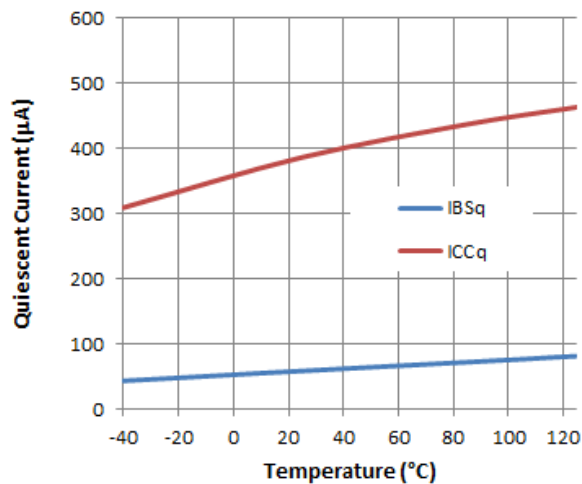


Figure 13. Quiescent Current vs. Temperature

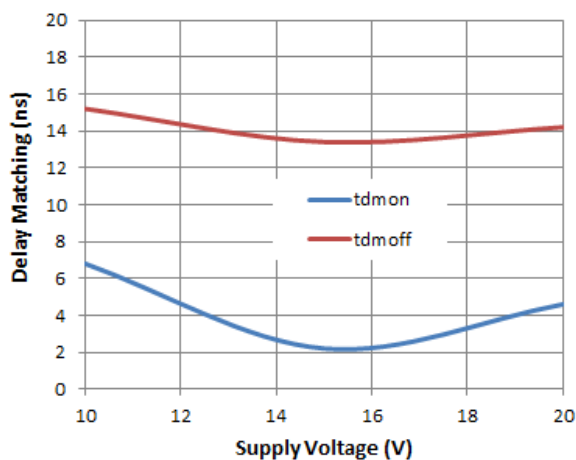


Figure 14. Delay Matching vs. Supply Voltage

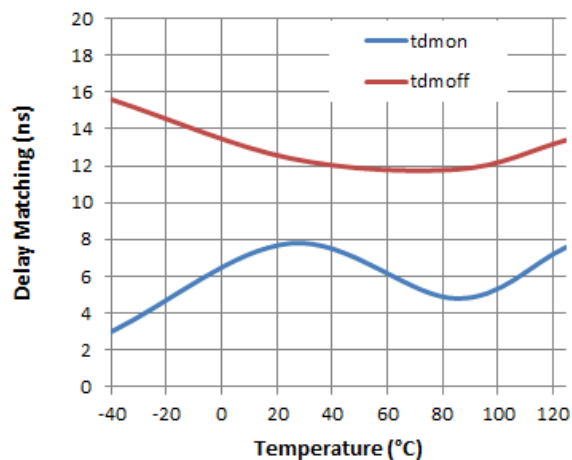


Figure 15. Delay Matching vs. Temperature

Typical Performance Characteristics (Cont.)

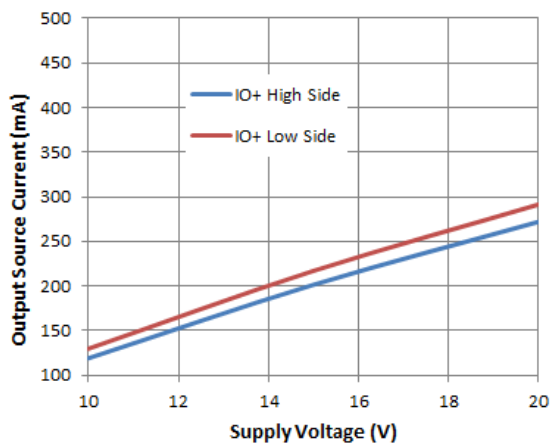


Figure 16. Output Source Current vs. Supply Voltage

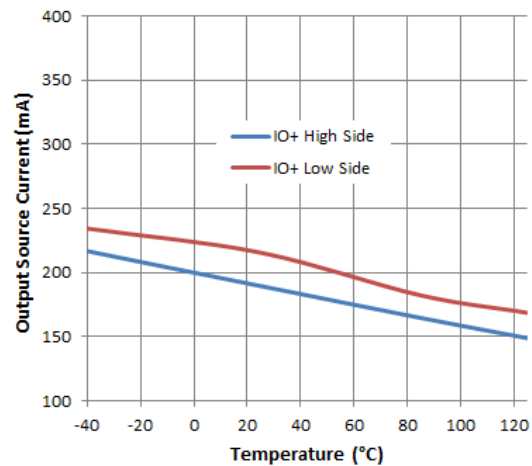


Figure 17. Output Source Current vs. Temperature

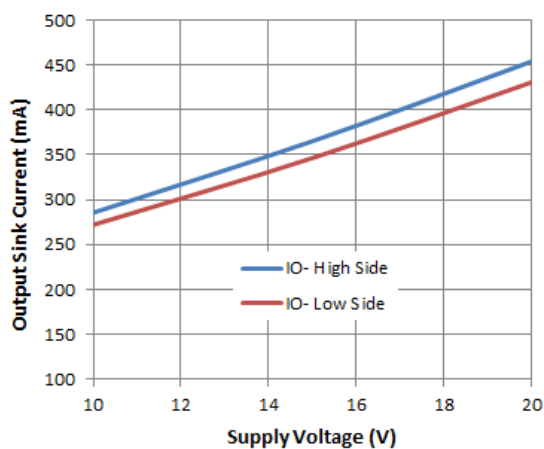


Figure 18. Output Sink Current vs. Supply Voltage

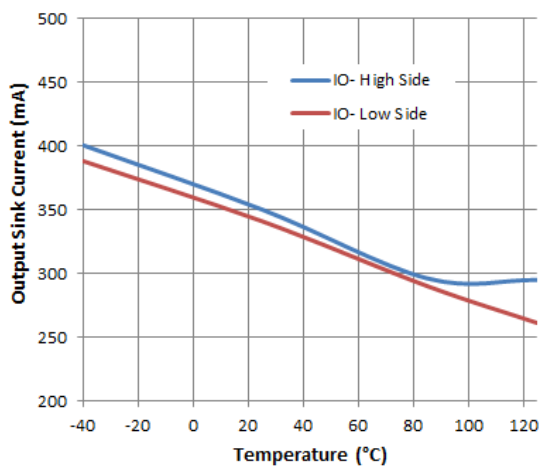


Figure 19. Output Sink Current vs. Temperature

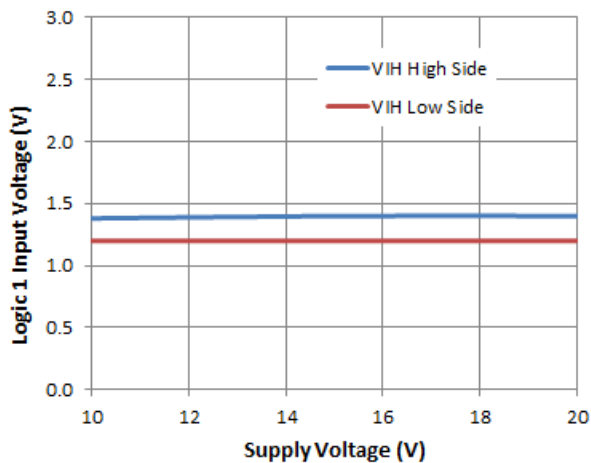


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

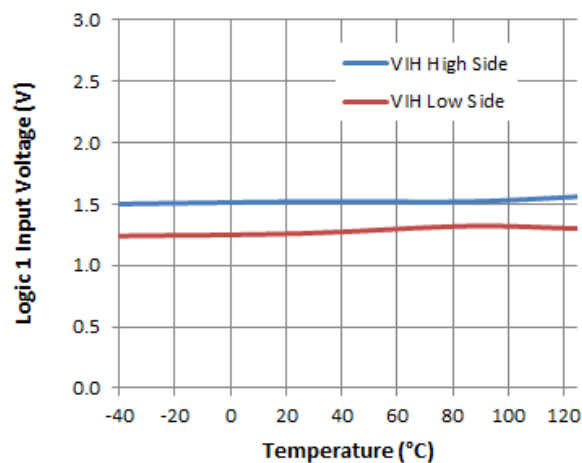


Figure 21. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (Cont.)

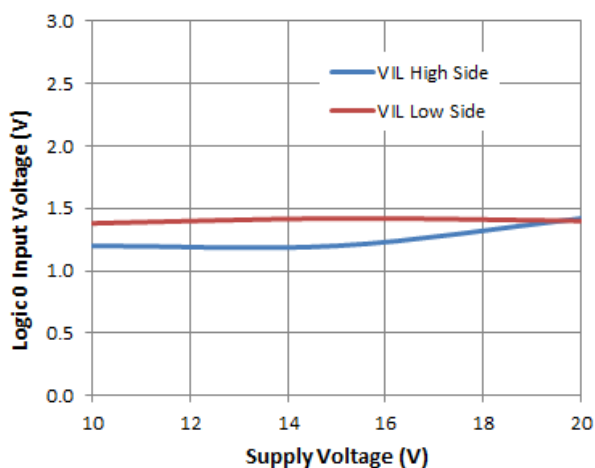


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

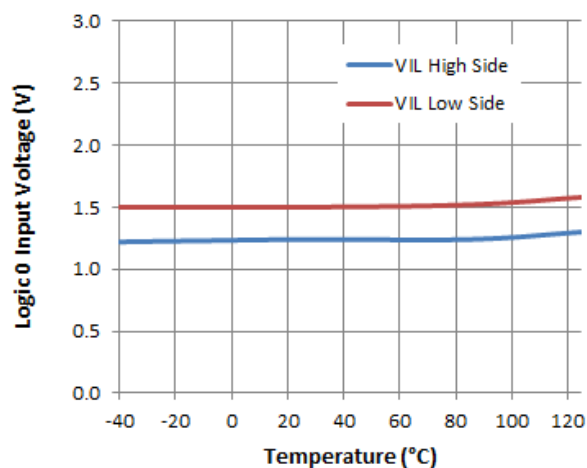


Figure 23. Logic 0 Input Voltage vs. Temperature

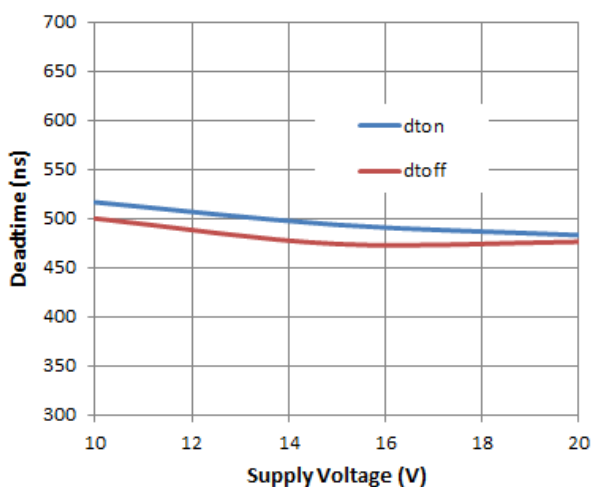


Figure 24. Deadtime vs. Supply Voltage

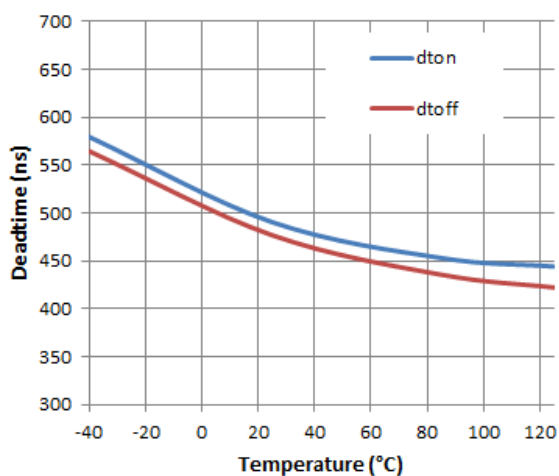


Figure 25. Deadtime vs. Temperature

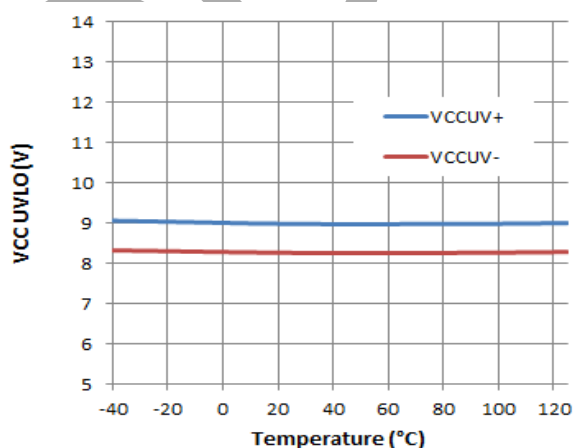


Figure 26. VCC UVLO vs. Temperature

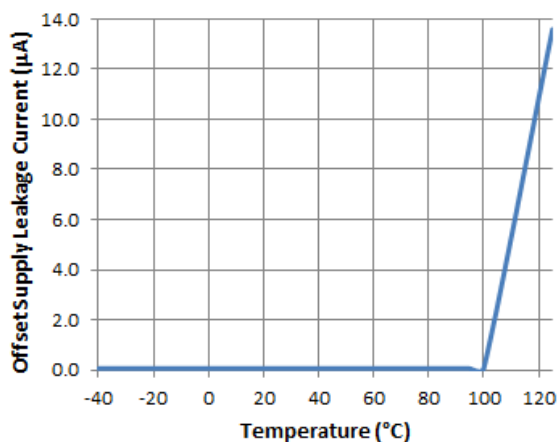
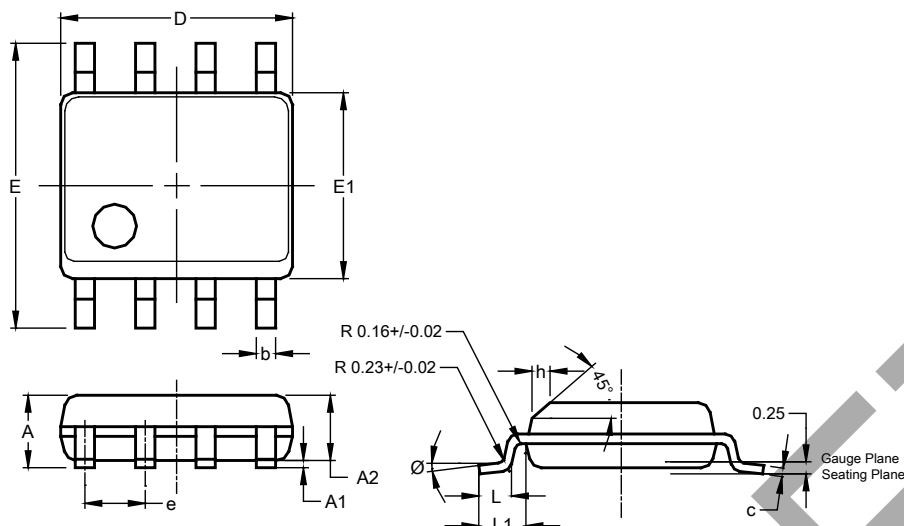


Figure 27. Offset Supply Leakage Current vs. Temperature

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8 (Type TH)

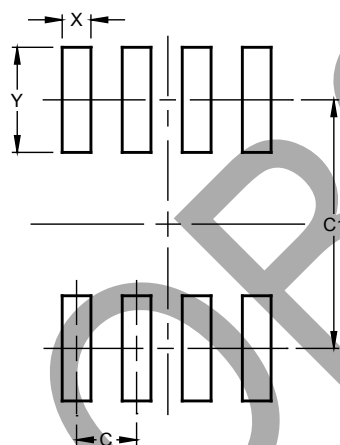


SO-8 (Type TH)			
Dim	Min	Max	Typ
A	1.35	1.75	--
A1	0.10	0.25	--
A2	--	--	1.45
b	0.35	0.51	--
c	0.190	0.248	--
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	--	--	1.27
h	0.25	0.50	--
L	0.41	1.27	--
L1	--	--	1.04
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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